

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEN-YUNG LEE	03/09/2022
SHAU-YU CHENG	03/09/2022
JHE-YI LIN	03/09/2022
CHUN-KAI TSENG	03/09/2022
WEI-HSUAN CHANG	03/09/2022
RECEIVING PARTY DATA	
Name:	REALTEK SEMICONDUCTOR CORPORATION
Street Address:	NO. 2, INNOVATION ROAD II, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	Taiwan ROC
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17692439
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	JUSTIN KING
SIGNATURE:	/Justin King/
DATE SIGNED:	03/11/2022
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I(we), WEN-YUNG LEE, SHAU-YU CHENG, JHE-YI LIN, CHUN-KAI TSENG and WEI-HSUAN CHANG whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled.

Wireless communication device and method

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

- ☐ United States Design Patent was
☐ executed on:
☐ filed on: Serial No.:
☐ established by PCT International Patent Application No.: filed: designating the
United States of America
☐ issued on _____ as U.S. Patent No.: _____

WHEREAS, **REALTEK SEMICONDUCTOR CORPORATION** whose post office address is **No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)** hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR NAME WEN-YUNG LEE	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor 	Date of Signature March 9, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME SHAU-YU CHENG	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Shau Yu Cheng</i>	Date of Signature March 9, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME JHE-YI LIN	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Jhe-Yi Lin</i>	Date of Signature March 9, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME CHUN-KAI TSENG	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Chun-Kai Tseng</i>	Date of Signature March 9, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME WEI-HSUAN CHANG	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Wei Hsuan Chang</i>	Date of Signature March 9, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)